

Applic. No. 10/765,584

Amdt. dated August 22, 2005

Reply to Office action of May 20, 2005

Claim Amendments

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Claim 1 (currently amended): A method for encapsulating ~~an a~~ plurality of electronic ~~component~~ components, which comprises:

joining a plurality of components together;

coating the plurality of components at the same time for  
providing ~~a-component~~ the plurality of components with a  
coating of a flowable coating material;

hardening the material of the coating;

subjecting the assembly including the plurality of components  
and the coating to at least one further process operation; and

completely encapsulating the assembly of the ~~component~~  
plurality of components and the coating in plastic.

Claim 2 (currently amended): The method according to claim 1,  
which further comprises applying the coating material to the  
~~component~~ plurality of components by immersion.

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Claim 3 (currently amended): The method according to claim 1, which further comprises carrying out the coating providing step by immersing the ~~component~~ plurality of components in the coating material.

Claim 4 (currently amended): The method according to claim 1, which further comprises applying the coating material to the ~~component~~ plurality of components by spraying.

Claim 5 (currently amended): The method according to claim 1, which further comprises carrying out the coating providing step by spraying the coating material on the ~~component~~ plurality of components.

Claim 6-7 (cancelled).

Claim 8 (currently amended): The method according to claim 1, which further comprises carrying out the coating providing step by applying the coating material to the ~~component~~ plurality of components by several successive coating operations.

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Claim 9 (original): The method according to claim 1, which further comprises carrying out the hardening step by supplying external heat.

Claim 10 (original): The method according to claim 1, which further comprises carrying out the hardening step by heating the coating.

Claim 11 (original): The method according to claim 1, which further comprises carrying out the hardening step by drying under environmental conditions.

Claim 12 (original): The method according to claim 1, which further comprises providing coating material of the coating with a high coefficient of expansion and good adhesion properties.

Claim 13 (original): The method according to claim 12, which further comprises selecting the coating material from a plastic selected from the group consisting of polyurethane and silicone.

Claim 14 (original): The method according to claim 1, which further comprises selecting the coating material from a

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plastic selected from the group consisting of polyurethane and silicone.

Claim 15 (cancelled).

Claim 16 (original): The method according to claim 1, which further comprises carrying out the plastic encapsulating step by injection molding the assembly with PBT.

Claim 17 (original): The method according to claim 1, which further comprises carrying out the plastic encapsulating step by encapsulating the assembly by injection molding PBT.

Claims 18-20 (cancelled).

Claim 21 (new): The method according to claim 1, wherein the at least one further process operation is welding the plurality of components to a conductor comb prior to the step of completely encapsulating in plastic.

Claim 22 (new): The method according to claim 21, wherein the completely encapsulating step is achieved by injection molding.

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Claim 23 (new): The method according to claim 22, further comprising separating the plurality of components by separating the conductor comb and encapsulating the separated components with a further encapsulation by injection molding.